### 506923409 10/14/2021

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6970245

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
BO TAO	10/08/2021
Li Wang	10/08/2021
Ching-Yang Wen	10/08/2021
Purakh Raj Verma	10/08/2021
ZHIBIAO ZHOU	10/08/2021
DONG YIN	10/08/2021
Gang Ren	10/08/2021
Jian Xie	10/08/2021

#### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17502026

#### **CORRESPONDENCE DATA**

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU

Address Line 1: 5F., NO.389, FUHE RD., YONGHE DIST.,

Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3929USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	10/14/2021

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## Title of Invention: SEMICONDUCTOR STRUCTURE

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I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are		(\$ 1.00), the receipt	of which is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, at	nd to any and all improveme ition and, in and to, all Letter r any continuations, continua	nts which are disclo 's Patent to be obtain ation-in-part, division	sed in the ned for said is, renewals,
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I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters Patent estify as to the same in any in	t and legal equivalent interference, litigation	nts as may be
representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be not IN WITNESS WHEREOF, I have he	olication, said invention and secessary or desirable to carry	said Letters Patent a y out the proposes ti	and said hereof.
Note: An application data sheet (PT0 inventive entity, must accompany thi			

Page 1 of 16

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

Inventor:	ROT	ΔΩ		Date:			
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F#NPO-P0002E-US1201 D\$B0-110U028216

## Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or	•			
☐ United States application nu	ımber	filed on		, or
☐ PCT international applicatio	n number	file	ed on	
The above-identified application was	made or authorized t	o be made by me.		
I believe that I am the original invent application.	or or an original joint i	nventor of a claime	ed invention in	the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				,
In consideration of the payment by	UNITED MICROE CORP.	LECTRONICS	having a pos	stal address of
No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Chu	ı City 300, T	aiwan, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar			receipt of whic	ch is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all impro tion and, in and to, all r any continuations, co	ovements which are Letters Patent to b ontinuation-in-part,	e disclosed in to be obtained for divisions, rene	the said ewals,
I hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement or h this assignment;	encumbrance has	been or will be	e made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters lestify as to the same in	Patent and legal ed any interference, l	quivalents as n litigation proce	nay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention ecessary or desirable t	n and said Letters F o carry out the pro	Patent and said poses thereof.	
Note: An application data sheet (PTG	D/SB/14 or equivalent)	, including naming	the entire	

Page 3 of 16

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

LEGAL NA	ME OF INVENT	OR(ASSIGNOR)		
Inventor:	Li Wang		Date:	Oct. Of. 2021
Signature:	WANG	4	**************************************	

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NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244 F#NPO-P0002E-US1201 DSB0-110U028216

PATENT

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☐ United States application no	United States application number		, or
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The above-identified application was	s made or authorized to be made	by me.	
I believe that I am the original inventapplication.	tor or an original joint inventor of a	claimed invention i	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impi			ile
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(referred to as "ASSIGNEE"below) t acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1.0 nd valuable consideration.	00), the receipt of wh	nich is hereby
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, a	nd to any and all improvements w ation and, in and to, all Letters Pat r any continuations, continuation-	hich are disclosed in ent to be obtained fo in-part, divisions, rer	n the or said newals,
I hereby covenant that no assignme entered into which would conflict wit	nt, sale, agreement or encumbrar h this assignment;	nce has been or will	be made or
I further covenant that ASSIGNEE wand documents relating to said inversement and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as rence, litigation prod	may be
representatives any and all papers, maintain, issue and enforce said ap equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention and said lecessary or desirable to carry out	etters Patent and s the proposes therec	of.
Note: An application data sheet (PTo inventive entity, must accompany the			

Page 5 of 16

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

LEGAL NA	ME OF INVENTOR(ASSIGNOR)		
Inventor:	Ching-Yang Wen	Date:	Oct. 08. 2021
Signature:	Wen Ching Yamp		

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F#NPO-P0002E-US1201 DSB0-110U028216

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

## Title of Invention: SEMICONDUCTOR STRUCTURE

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The above-identified application was	made or authorized to be n	nade by me.		
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No.3, Li-Hsin Road 2, Science	-Based Industrial Park	, Hsin-Chu City	300, Taiwan, R.O.0	
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		(\$ 1.00), the receipt	of which is hereby	
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improveme tion and, in and to, all Letter rany continuations, continua	nts which are disclors Patent to be obtaination-in-part, division	osed in the ined for said ns, renewals,	
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire				

Page 7 of 16

inventive entity, must accompany this form. Use this form for each additional inventor.

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

LEGAL WANTE OF INVENTOR (ASSIGNOR)				
Inventor:	Purakh Raj Verma	Date:	Oct. 08. 2021	
Signature:	PURAKH RAJ VERMA		1	

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NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244 F#NPO-P0002E-US1201 DSB0-110U028216

PATENT

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representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have he	olication, said invention an ecessary or desirable to ca	d said Letters f arry out the pro	Patent and sa poses thereo	of.
Note: An application data sheet (PT0 inventive entity, must accompany thi				

Page 9 of 16

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

LEGAL NAME OF INVENTOR(ASSIGNOR)					
Inventor:	ZHIBIAO ZHOU	Date:	Oct 08 2021		
Signature:	- Thou	This bins			

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NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244 F#NPO-P0002E-US1201 DSB0-110U028216

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Note: An application data sheet (DT)	NSR/14 or equivalent) including	naming the entire	

Page 11 of 16

inventive entity, must accompany this form. Use this form for each additional inventor.

LEGAL NAME OF INVENTOR(ASSIGNOR)			
Inventor:	DONG YIN	Date:Oct . 0	
Signature:	YIN DONA		_

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NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244 F#NPO-P0002E-US1201 DSB0-110U028216

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NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

LEGAL NA	WE OF INVENTOR(ASSIG	NOR)
Inventor:	Gang Ren	Date: Oct. 08. 202/
Signature;	REN GANG	

Page 14 of 16

NPO#NAU-P3929-USA:0 -CUST#UMCD-2021-0244 F#NPO-P0002E-US1201 DSB0-110U028216

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Page 15 of 16

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244

LEGAL NA	ME OF INVEN	HOR(ASS	GNOR)	
Inventor:	Jian Xie		Date:	Oct. 0f 2021
Signature:	Jian	Xie		

NPO#NAU-P3929-USA:0 CUST#UMCD-2021-0244 Page 16 of 16

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